

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS300N08S5N014	**Issued**	03. June 2021
MA#	MA005344607		
Package	PG-HSOG-8-1	**Weight***	707.88 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.440	0.91	0.91	9097	9097
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		190	
	non noble metal	copper	7440-50-8	134.219	18.96	18.99	189607	189854
wire	non noble metal	aluminium	7429-90-5	19.808	2.80	2.80	27982	27982
encapsulation	inorganic material	zincoxide	1314-13-2	2.573	0.36		3635	
	miscellaneous	miscellaneous	-	10.293	1.45		14540	
	plastics	epoxy resin	-	38.597	5.45		54525	
	inorganic material	silicondioxide	60676-86-0	205.851	29.08	36.34	290799	363499
leadfinish	non noble metal	tin	7440-31-5	8.309	1.17	1.17	11738	11738
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	310	311
solder	non noble metal	tin	7440-31-5	0.107	0.02		151	
	noble metal	silver	7440-22-4	0.133	0.02		188	
	non noble metal	lead	7439-92-1	5.093	0.72	0.76	7194	7533
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		117	
	non noble metal	iron	7439-89-6	0.276	0.04		390	
	non noble metal	copper	7440-50-8	275.705	38.95	39.00	389479	389986
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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